

Surface Mount Technology Association Press Release

For more info contact:
JoAnn Stromberg
952-920-7682
joann@smta.org



For immediate release - August 23, 2011

SMTA International Focuses on Package-on-Package

Minneapolis, MN - The SMTA announced that it will hold sessions and a tutorial on Package-on-Package (PoP) surface mount stacking at their annual conference, SMTA International, taking place October 16-20, 2011 in Ft. Worth, Texas.

Lee Smith, Amkor Technology, will chair a session titled "Assembly Solutions for Next Generation Package on Package (PoP) Requirements" which will feature presentations from Intel Corporation, Qualcomm, Rambus Inc. Smith commented that, "Package-on-Package (PoP) surface mount stacking has seen widespread adoption over the last 5 years. Today nearly every smartphone and media tablet in the world specifies PoP for their signal processing and memory architecture, resulting in over 11 million packages surface mount stacked per week. SMTAI continues to be the conference where leading edge PoP technologies are discussed openly across the electronics supply chain." A second PoP-related session titled "Process and Reliability Characterization of PoP Materials and SMT Processes," chaired by Sheldon Schwandt of Research In Motion, will feature papers from Amkor Technology, Flextronics, and Universal Instruments Corporation. Additionally, a presentation from ZESTRON America, during the SMT6 session, introduces the question "Is Cleaning Critical to PoP Assemblies?"

<http://www.smta.org/smtai/tech.cfm#aat2>

Lee Smith will also deliver the Opening Session presentation, "Package on Package (PoP): Past, Present and Future" on Tuesday, October 18. The session is open to all attendees.

http://www.smta.org/smtai/special_events.cfm#oc

Charles Bauer, Ph.D., TechLead Corporation, will instruct a half-day course on "3D Assembly... CSP to PoP to Board." The tutorial covers both the fundamental and advanced technologies that today produce stacked chip packages and assemblies as well as stackable packages for implementation of highly integrated electronic products. These include the challenges of die thinning, thin die attach, multi-level wire bonding, mixed technology die attachment and bonding, flip chip, TAB and TSV technologies.

<http://www.smta.org/smtai/tutorials.cfm>

Details about SMTA International can be found online at <http://smta.org/smtai> or contact SMTA administrator JoAnn Stromberg: 952-920-7682 or joann@smta.org.

The SMTA membership is an international network of professionals who build skills, share practical experience and develop solutions in electronic assembly technologies, including microsystems, emerging technologies, and related business operations.

-End-